



DuPont™ SAC™

Semi-Aqueous Chemistry Remover

Aqueous-organic formulations that quickly and completely remove all types of post-etch residue under ambient conditions

The DuPont™ SAC™ semi-aqueous chemistry remover series of products comprise a highly effective and elegant solution to the cleaning of etch residue at or below critical dimensions of 0.25 µm. Used at ambient temperature for short process times, DuPont™ SAC™ products eliminate W plug failures and facilitate advanced interconnect by complete cleaning of subtractive etch structures. Compatible with a wide variety of low-k dielectrics as well as Cu, Al, W and all commonly used barrier materials, these products are water rinseable and provide wide process latitude and long bath life. Their excellent surface activity reduces surface metal ion contamination by several orders of magnitude, offering a dramatic improvement over alternate cleaning strategies including other wet/dry or ashing technologies.

Each DuPont SAC™ formulation is tailored ideally to service a particular niche within advanced interconnect cleaning. However, the diversity of different process integration schemes that exist mandates that these classifications serve as a guide only.

DuPont™ SAC™ series semi-aqueous chemistry removers include:

EKC630™

This chemistry is designed for use in wet bench applications for cleaning metal and via processes. Compatible with all standard materials employed in advanced interconnect. Room temperature operation for 2–5 minutes is typical, followed by a water rinse.

EKC640™

Specifically conceived for single wafer tool applications, EKC640™ is a fast-acting cleaning chemistry best suited for situations where a premium is placed on high throughput. However, the quick, effective performance of the product does not preclude its delivery to the wafer surface by other methods.

EKC652™

This chemistry has been fine-tuned for applications involving highly sensitive low-k dielectrics. This product is flexible for use in either a spray tool or wet bench, to be followed by a DI rinse.

DuPont EKC Technology Support

DuPont EKC Technology offers applications engineering support for all products. This includes product development and sustaining engineering solutions. On-site consulting, process evaluation and/or additional wafer testing are available through EKC's applications engineering or R&D as needed.



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For more information on DuPont™ SAC™ or other DuPont products, please visit our website.

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CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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